

STRUCTURES FOR IMPLEMENTING INTEGRATED CONDUCTOR AND CAPACITOR IN SMD PACKAGING

Abstract of the Disclosure

5 Structures are provided for implementing an integrated conductor and
capacitor in a surface mounted device (SMD) package. A first pair and a
second pair of contacts contained within the SMD package respectively are
provided in mating engagement with a first pair and a second pair of
corresponding SMD package contacts. A conductor extends between the
10 first pair of contacts, contained within the SMD package. A capacitor is
defined between the second pair of contacts, contained within the SMD
package. An additional one or pair of integral capacitors optionally is
provided for providing additional capacitance to ground to decouple common
mode noise from the power planes.